

June 2010

SG6961 Critical Conduction Mode PFC Controller

Features

- Boundary Mode PFC Controller
- Low Input Current THD
- Controlled On-Time PWM
- Zero-Current Detection
- Cycle-by-cycle Current Limiting
- Leading-Edge Blanking Instead of RC Filtering
- Low Startup Current: 10µA (Typical)
- Low Operating Current: 4.5mA (Typical)
- Feedback Open-Loop Protection
- Programmable Maximum On-Time
- Output Over-Voltage Clamping Protection
- Clamped Gate Output Voltage 16.5V

Applications

- Electric Lamp Ballasts
- AC-DC Switching Mode Power Converter
- Open-Frame Power Supplies and Power Adapters

Description

The SG6961 is an 8-pin boundary mode PFC controller IC intended for controlling PFC pre-regulators. The SG6961 provides a controlled on-time to regulate the output DC voltage and achieve natural power factor correction. The maximum on-time of the external switch is programmable to ensure safe operation during AC brownouts. An innovative multi-vector error amplifier is built in to provide rapid transient response and precise output voltage clamping. A built-in circuit disables the controller if the output feedback loop is opened. The startup current is lower than 20µA and the operating current is under 4.5mA. The supply voltage can be up to 20V, maximizing application flexibility.

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method	
SG6961SZ	-30°C to +85°C	8-Pin Small Outline Package (SOP)	Tape & Reel	
SG6961DZ	-30°C to +85°C	8-Pin Dual Inline Package (DIP)	Tube	
SG6961SY	-30°C to +85°C	8-Pin Small Outline Package (SOP)	Tape & Reel	

Application Circuit

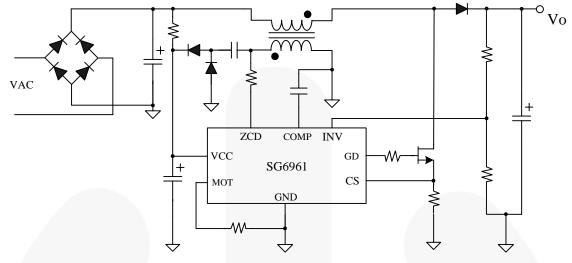


Figure 1. Typical Application

Block Diagram

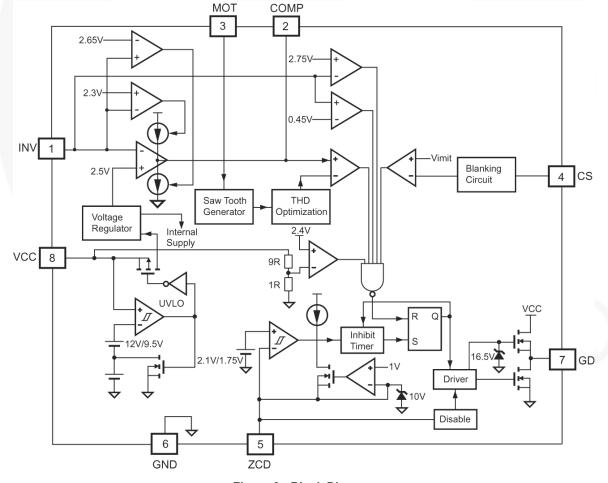
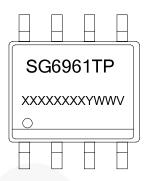
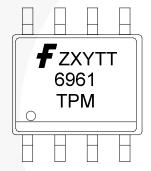


Figure 2. Block Diagram

Marking Information



- Marking for SG6961SZ (pb-free)
- Marking for SG6961DZ (pb-free)



Marking for SG6961SY (Green-Compound)

- T- D=DIP, S=SOP
- P- Z=Lead Free + ROHS Compatible Null=Regular Package
- XXXXXXXX- Wafer Lot
- Y: Year; WW: Week
- V: Assembly Location

- **f**: Fairchild Logo
- Z: Plant Code
- X: Year Code
- Y: Week Code
- TT: Die Run Code
 T: Package Type (S = SOP)
- P: Y = Green Compound
- M: Manufacturing Flow Code

Figure 3. Top Mark

Pin Configuration

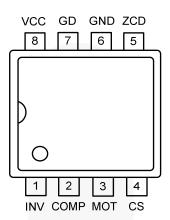


Figure 4. Pin Configuration

Pin Definitions

Pin#	Name	Description				
1	INV	Inverting Input of the Error Amplifier. INV is connected to the converter output via a resistive divider. This pin is also used for over-voltage clamping and open-loop feedback protection.				
2	COMP	The Output of the Error Amplifier. To create a precise clamping protection, a compensation network between this pin and GND is suggested.				
3	MOT	Maximum On Time . A resistor from MOT to GND is used to determine the maximum on-time of the external power MOSFET. The maximum output power of the converter is a function of the maximum on time.				
4	CS	Current Sense . Input to the over-current protection comparator. When the sensed voltage across the sense resistor reaches the internal threshold (0.8V), the switch is turned off to activate cycle-by-cycle current limiting.				
5	ZCD	Zero Current Detection . This pin is connected to an auxiliary winding via a resistor to detect the zero crossing of the switch current. When the zero crossing is detected, a new switching cycle is started. If it is connected to GND, the device is disabled.				
6	GND	Ground . The power ground and signal ground. Placing a 0.1µF decoupling capacitor between VCC and GND is recommended.				
7	GD	Driver Output . Totem-pole driver output to drive the external power MOSFET. The clamped gate output voltage is 16.5V.				
8	VCC	Power Supply. Driver and control circuit supply voltage.				

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V _{VCC}	DC Supply Voltage	DC Supply Voltage		25	V
V _{HIGH}	Gate Driver		-0.3	25.0	V
V_{LOW}	Others (INV, COMP, MOT, CS)		-0.3	7.0	V
V _{ZCD}	Input Voltage to ZCD Pin		-0.3	12.0	V
Б	De la Birata di la	SOP		400	mW
P_D	Power Dissipation	DIP		800	
TJ	Operating Junction Temperature		-40	+150	°C
0	Thermal Desistance, lunction to Air	SOP		62.70	°C/W
θ_{JA}	Thermal Resistance; Junction-to-Air	DIP		48.45	
T _{STG}	Storage Temperature Range		-55	+150	°C
/	Lead Temperature	SOP		+230	
	Wave Soldering or IR, 10 Seconds)	DIP		+260	°C
ESD E	Floring District Condition	Human Body Model, JESD22-A114		2	KV
	Electrostatic Discharge Capability	Machine Model, JESD22-A115		200	V

Notes:

- 1. All voltage values, except differential voltage, are given with respect to GND pin.
- 2. Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
T _A	Operating Ambient Temperature	-30	+85	°C

Electrical Characteristics

 V_{CC} =15V, T_{A} =25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units	
V _{CC} Section		1	1		·	I	
V _{CC-OP}	Continuous Operation Voltage				20	V	
V _{CC-ON}	Turn-on Threshold Voltage		11	12	13	V	
V _{CC-OFF}	Turn-off Threshold Voltage		8.5	9.5	10.5	V	
I _{CC-ST}	Startup Current	V _{CC} =V _{CC-ON} - 0.16V		10	20	μΑ	
I _{CC-OP}	Operating Supply Current	V _{CC} =12V, V _{CS} =0V, C _L =3nF, f _{SW} =60KHz		4.5	6.0	mA	
$V_{\text{CC-OVP}}$	V _{DD} Over-Voltage Protection Level			24		V	
t _{D-VCCOVP}	V _{DD} Over-Voltage Protection Debounce			30		μs	
Error Amplifie	er Section						
V_{REF}	Reference Voltage		2.475	2.500	2.525	V	
Gm	Transconductance	T _A =25°C	100	125	150	μΩ	
V _{INVH}	Clamp High Feedback Voltage			2.65	2.70	V	
V_{INVL}	Clamp Low Feedback Voltage		2.25	2.30		V	
V _{OUT} HIGH	Output High Voltage		4.8			V	
V _{OZ}	Zero Duty Cycle Output Voltage		1.15	1.25	1.35	V	
V _{INV-OVP}	Over Voltage Protection for INV Input			2.75		V	
V _{INV-UVP}	Under Voltage Protection for INV Input		0.40	0.45	0.50	٧	
	Source Current	V _{INV} =2.35V, V _{COMP} =1.5V	7	20			
I _{COMP}	Source Current	V _{INV} =1.5V,	450	800		μΑ	
	Sink Current	V _{INV} =2.65V, V _{COMP} =5V	10	20			

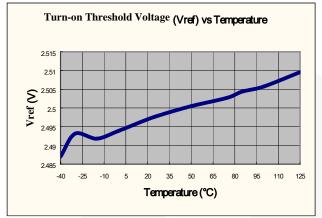
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Electrical Characteristics

 V_{CC} =15V, T_{A} =25°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Current-Sense	e Section					
V_{PK}	Threshold Voltage for Peak Current Limit Cycle- by-Cycle Limit		0.77	0.82	0.87	V
t _{PD}	Propagation Delay				200	ns
t_{LEB}	Leading-Edge Blanking Time	R _{MOT} =24kΩ		400	500	ns
Gate Section						
V_{ZOUT}	Output Voltage Maximum (Clamp)	V _{CC} =20V	15.5	16.5	17.5	V
V _{OL}	Output Voltage Low	V _{CC} =15V, I _O =100mA	1		1.4	V
V_{OH}	Output Voltage High	V _{CC} =14V, I _O =100mA	8			V
t _R	Rising Time	V _{CC} =12V, C _L =3nF, 20~80%	50	80	160	
t _F	Falling Time	V _{CC} =12V, C _L =3nF, 80~20%	30	40	70	ns
Zero Current	Detection Section					
V_{ZCD}	Input Threshold Voltage Rising Edge	V _{ZCD} Increasing	1.9	2.1	2.3	V
H _{YS} of V _{ZCD}	Threshold Voltage Hysteresis	V _{ZCD} Decreasing	0.25	0.35	0.50	V
V _{ZCD-HIGH}	Upper Clamp Voltage	I _{ZCD} =3mA	8	10	12	V
V _{ZCD-LOW}	Lower Clamp Voltage	I _{ZCD} =-0.5mA	0			V
t _{DEAD}	Maximum Delay, ZCD to Output Turn-On	V _{COMP} =5V, f _{SW} =60KHz	100		400	ns
t _{RESTART}	Restart Time	Output Turned Off by ZCD	300	500	700	μs
t _{INHIB}	Inhibit Time (Maximum Switching Frequency Limit)	R _{MOT} =24kΩ	1.5	2.5	3.0	μs
V _{DIS}	Disable Threshold Voltage		200	250	300	mV
t _{ZCD-DIS}	Disable Function Debounce Time	R_{MOT} =24k Ω , V_{ZCD} =100m V	800		y	μs
Maximum On-	Time Section					
V _{мот}	Maximum On Time Voltage		1.25	1.30	1.35	V
t _{ON-MAX}	Maximum On Time Programming (Resistor Based)	R_{MOT} =24k Ω , V_{CS} =0V, V_{COMP} =5V	21	25	27	μs

Typical Performance Characteristics



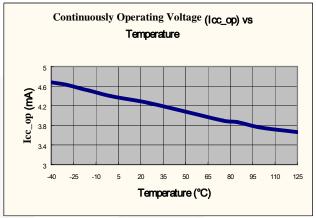
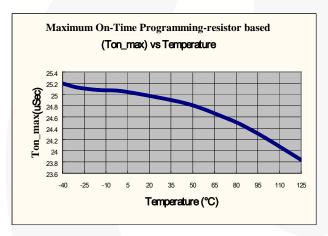


Figure 5. Turn-On Threshold Voltage





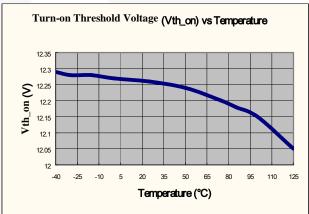
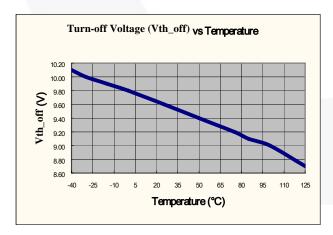


Figure 7. Maximum On-Time

Figure 8. Turn-On Threshold Voltage



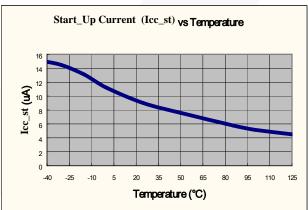
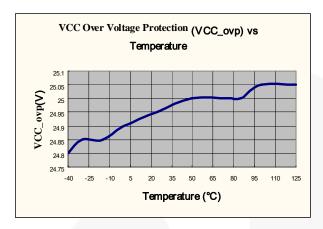


Figure 9. Turn-Off Voltage

Figure 10. Startup Current

Typical Performance Characteristics (Continued)



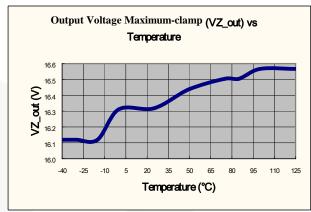


Figure 11. Vcc Over-Voltage Protection

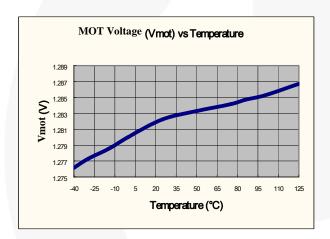


Figure 12. Output Voltage Maximum-Clamp

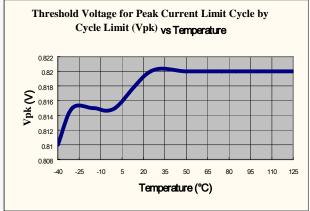


Figure 13. MOT Voltage

Figure 14. Threshold Voltage for Peak Current Limit

Functional Description

Error Amplifier

The inverting input of the error amplifier is referenced to INV. The output of the error amplifier is referenced to COMP. The non-inverting input is internally connected to a fixed $2.5V \pm 2\%$ voltage. The output of the error amplifier is used to determine the on-time of the PWM output and regulate the output voltage. To achieve a low input current THD, the variation of the on time within one input AC cycle should be very small. A multivector error amplifier is built in to provide fast transient response and precise output voltage clamping.

For SG6961, connecting a capacitance, such as 1µF, between COMP and GND is suggested. The error amplifier is a trans-conductance amplifier that converts voltage to current with a 125µmho.

Startup Current

Typical startup current is less than 20 μ A. This ultra-low startup current allows the usage of high resistance, low-wattage startup resistor. For example, 1 M Ω /0.25W startup resistor and a 10 μ F/25V (V_{CC} hold-up) capacitor are recommended for an AC-to-DC power adaptor with a wide input range 85 to 265V_{AC}.

Operating Current

Operating current is typically 4.5mA. The low operating current enables a better efficiency and reduces the requirement of V_{CC} hold-up capacitance.

Maximum On-Time Operation

Given a fixed inductor value and maximum output power, the relationship between on-time and line voltage is:

$$t_{ON} = \frac{2 \cdot L \cdot P_O}{V_{rms}^2 \cdot \eta} \tag{1}$$

If the line voltage is too low or the inductor value is too high, t_{ON} is too long. To avoid extra low operating frequency and achieve brownout protection, the maximum value of t_{ON} is programmable by one resistor, R_I , connected between MOT and GND. A 24k Ω resistor R_I generates corresponds to 25 μ s maximum on time:

$$t_{ONMAX} = R_I(k\Omega) \bullet \frac{25}{24} (\mu S)$$
 (2)

The range of the maximum on-time is designed as 10 \sim 50 μ s.

Peak Current Limiting

The switch current is sensed by one resistor. The signal is feed into CS pin and an input terminal of a comparator. A high voltage in CS pin terminates a switching cycle immediately and cycle-by-cycle current limit is achieved. The designed threshold of the protection point is 0.82V.

Leading-Edge Blanking (LEB)

A turn-on spike on CS pin appears when the power MOSFET is switched on. At the beginning of each switching pulse, the current-limit comparator is disabled for around 400ns to avoid premature termination. The gate drive output cannot be switched off during the blanking period. Conventional RC filtering is not necessary, so the propagation delay of current limit protection can be minimized.

Under-Voltage Lockout (UVLO)

The turn-on and turn-off threshold voltage is fixed internally at 12V/9.5V. This hysteresis behavior guarantees a one-shot startup with proper startup resistor and hold-up capacitor. With an ultra-low startup current of 20µA, one 1M Ω R_{IN} is sufficient for startup under low input line voltage, $85V_{\text{rms}}.$ Power dissipation on R_{IN} would be less than 0.1W even under high line $(V_{\text{AC}}\!=\!265V_{\text{rms}})$ condition.

Output Driver

With low on resistance and high current driving capability, the output driver can drive an external capacitive load larger than 3000pF. Cross conduction current has been avoided to minimize heat dissipation, improving efficiency and reliability. This output driver is internally clamped by a 16.5V Zener diode.

Zero-Current Detection (ZCD)

The zero-current detection of the inductor is achieved using its auxiliary winding. When the stored energy of the inductor is fully released to output, the voltage on ZCD goes down and a new switching cycle is enabled after a ZCD trigger. The power MOSFET is always turned on with zero inductor current such that turn-on loss and noise can be minimized. The converter works in boundary mode and peak inductor current is always exactly twice of the average current. A natural power factor correction function is achieved with the low-bandwidth, on-time modulation. An inherent maximum off time is built in to ensure proper startup operation. This ZCD pin can be used as a synchronous input.

Noise Immunity

Noise on the current sense or control signal can cause significant pulse-width jitter, particularly in the boundary-mode operation. Slope compensation and built-in debounce circuit can alleviate this problem. Because the SG6961 has a single ground pin, high sink current at the output cannot be returned separately. Good high-frequency or RF layout practices should be followed. Avoiding long PCB traces and component leads, locating compensation and filter components near to the FAN6961, and increasing the power MOSFET gate resistance improve performance.

Reference Circuit

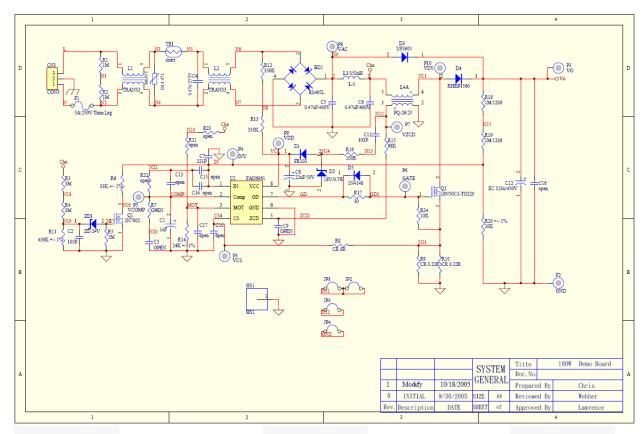
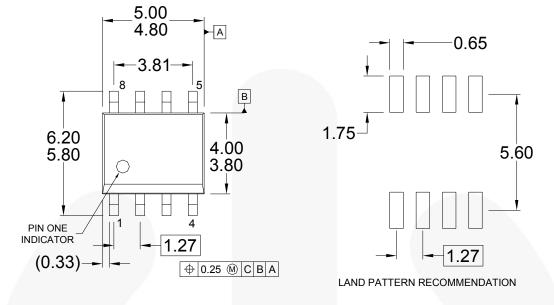
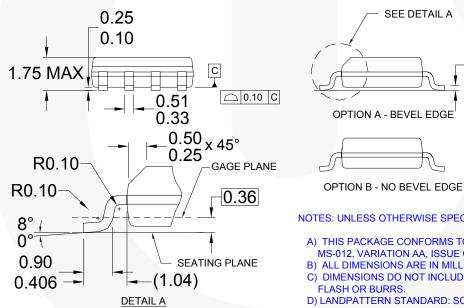
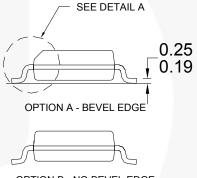


Figure 15. Reference Circuit

Physical Dimensions







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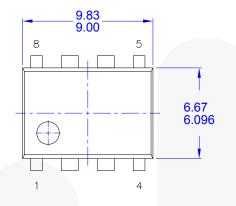
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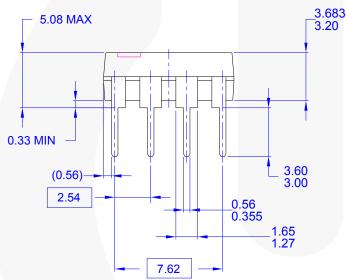
Figure 16. 8-Pin, Small Outline Package (SOP)

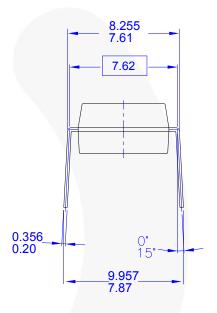
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Figure 17. 8-Pin, Dual Inline Package (DIP)





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